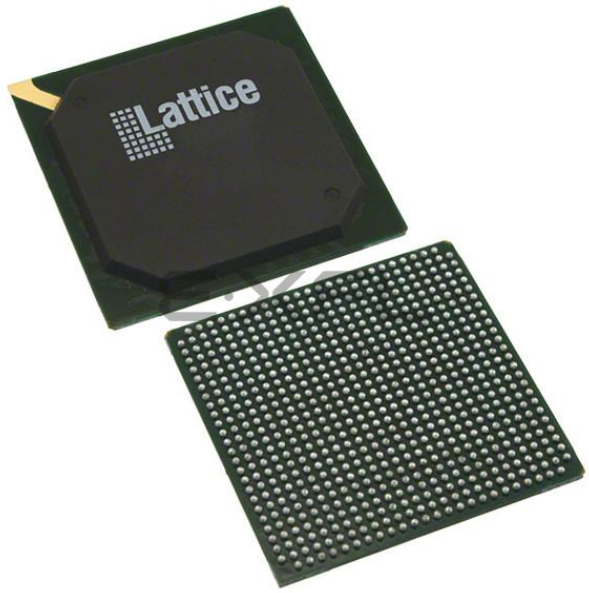
Lattice Semiconductor Corporation - LC51024MV-75F672I Datasheet



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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	32
Number of Macrocells	1024
Number of Gates	-
Number of I/O	381
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc51024mv-75f672i

Table 4. MFB Memory Configuration

Memory Mode	Max. Configuration Size[1]
Dual-port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 8 512 x 16
Single-port, Pseudo Dual Port, FIFO	16,384 x1 8,192 x 2 4,096 x 4 2,048 x 8 1,024 x 16 512 x 32
CAM	128 x 48

1. Smaller configurations are possible.

Input and Output
The data input and control signals to a MFB in memory mode are generated from inputs from the routing. Data signals are only available in the true non-inverted format. True or complemented versions of the inputs are available for generating the control signals. Data and flag outputs are fed from the MFB to the GRP and OSA. Unused inputs and outputs are not accessible in memory mode.

ROM Operation
In each of the memory modes it is possible to specify the power-on state of each bit in the memory array. This allows the memory to be used as ROM if desired.

Increased Depth And Width
Designs that require a memory depth or width that is greater than that support by a single MFB can be supported by cascading multiple blocks. For dual port, single port, and pseudo dual port modes additional width is easily provided by sharing address lines. Additional depth is supported by multiplexing the RAM output. For FIFO and CAM modes additional width is supported through the cascading of MFBs.

The Lattice design tools automatically combine blocks to support the memory size specified in the user's design.

Bus Size Matching
All of the memory modes apart from CAM mode support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies this mapping scheme applies to each port.

FIFO Mode

In FIFO Mode the multi-function array is configured as a FIFO (First In First Out) buffer with built in control. The read and write clocks can be different or the same dependent on the application. Four flags show the status of the FIFO; Full, Empty, Almost Full, and Almost Empty. The thresholds for Full, Almost full and Almost empty are programmable by the user. It is possible to reset the read pointer, allowing support of frame retransmit in communications applications. If desired, the block can be used in show ahead mode allowing the early reading of the next read address.

In this mode one ports accesses 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 12 shows the block diagram of the FIFO.

Write data, write enable, flag outputs and read enable are synchronous. The Write Data, Almost Full and Full share the same clock and clock enables. Read outputs are synchronous although these can be configured in look ahead mode. The Read Data, Empty and Almost Empty signals share the same clock and clock enables. Reset is shared by all signals. Table 8 shows the possible sources for the clock, clock enable and reset signals for the various registers.

Figure 12. FIFO Block Diagram

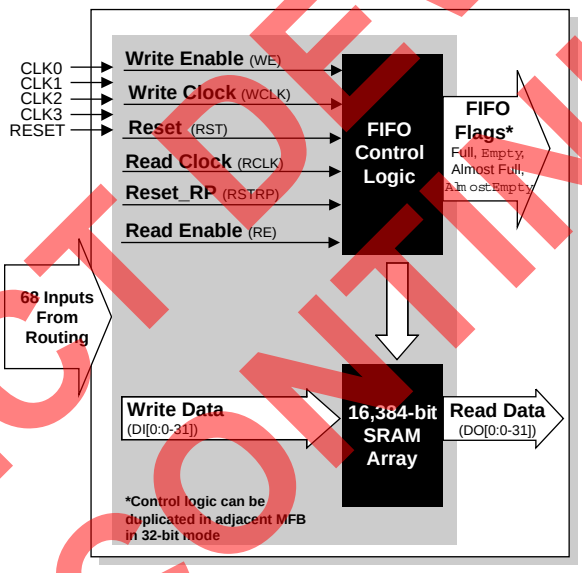

Table 8. Register Clocks, Clock Enables, and Initialization in FIFO Mode

Register	Input	Source
Write Data, Write Enable	Clock	WCLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	N/A
Full and Almost Full Flags	Clock	WCLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.
Read Data, Empty and Almost Empty Flags	Clock	RCLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	RE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.

sysCONFIG Interface

In addition to being able to program the device through the IEEE 1532 interface a microprocessor style interface (sysCONFIG interface) allows reconfiguration of the SRAM bits within the device. For more information on the sysCONFIG capability, refer to TN1026, ispXP Configuration Usage Guidelines.

Security Scheme

A programmable security scheme is provided on the ispXPLD 5000MX devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Low Power Consumption

The ispXPLD 5000MX devices use zero power non-volatile cells along with full CMOS design to provide low static power consumption. The 1.8V core reduces dynamic power consumption compared with devices with higher core voltages. For information on estimating power consumption, refer to TN1031 Power Estimation in ispXPLD 5000MX Devices.

Density Migration

The ispXPLD 5000MX family has been designed to ensure that different density devices in the same package have compatible pin-outs. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispXPLD 5000MX devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal boundary scan registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispXPLD 5000MX family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

Absolute Maximum Ratings[1, 2, 3]

	ispXPLD 5000MC 1.8V	ispXPLD 5000MB/V 2.5V/3.3V
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V
PLL Supply Voltage (V_{CCP})	-0.5 to 2.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V
IEEE 1149.1 TAP Supply Voltage (V_{CCJ})	-0.5 to 4.5V	-0.5 to 4.5V
Input Voltage Applied[4, 5]	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C
Junction Temperature (T_J) with Power Applied	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied (while programming, following the programming specifications).
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Overshoot and Undershoot of -2V to (V_{IHMAX} +2) volts not to exceed 6V is permitted for a duration of <20ns.
5. A maximum of 64 I/Os per device with V_{IN} > 3.6V is allowed.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Supply Voltage for 1.8V Devices (ispXPLD 5000MC)	1.65	1.95	V
	Supply Voltage for 2.5V Devices (ispXPLD 5000MB)	2.3	2.7	V
	Supply Voltage for 3.3V Devices (ispXPLD 5000MV)	3	3.6	V
V_{CCP}	PLL Block Supply Voltage for PLL 1.8V Devices	1.65	1.95	V
	PLL Block Supply Voltage for PLL 2.5V Devices	2.3	2.7	V
	PLL Block Supply Voltage for PLL 3.3V Devices	3	3.6	V
T_J	Junction Temperature (Commercial Operation)	0	90	C
	Junction Temperature (Industrial Operation)	-40	105	C

E²CMOS Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle[1]	1,000	—	Cycles

1. Valid over commercial temperature range.

Hot Socketing Characteristics[1, 2, 3, 4]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	0 ð V_{IN} ð 3.0V	—	+/-50	+/-800	µA

1. Insensitive to sequence of V_{CC} and V_{CCO} when V_{CCO}þð 1.0V. For V_{CCO} > 1.0V, V_{CC} min must be present. However, assumes monotonic rise/fall rates for V_{CC} and $V_{CCO,}$ provided (V_{IN} - V_{CCO})þð 3.6V.
2. 0 ð V_{CC} ð V_{CC} (MAX), 0 ð V_{CCO} ð V_{CCO} (MAX)
3. I_{DK} is additive to I_{PU}, I_{PD} or I_{BH}. Device defaults to pull-up until non-volatile cells are active.
4. LVTTL, LVCMOS only.

ispXPLD 5000MX Family External Switching Characteristics (Continued)[1, 2, 3]

Over Recommended Operating Conditions

Parameter	Description	-4		-45		-5		-52		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
f_{MAX} (RAM)[5]	Clock Frequency to RAM in:											
	Single Port Mode	—	155	—	155	—	155	—	155	—	93	MHz
	Dual Port Mode	—	155	—	155	—	155	—	155	—	93	MHz
	Pseudo Dual Port Mode	—	180	—	180	—	160	—	160	—	106	MHz
f_{MAX} (FIFO)[5]	Clock Frequency to FIFO	—	225	—	220	—	210	—	210	—	132	MHz
t_{PWR_ON}	Power-on Time	—	200	—	200	—	200	—	200	—	200	µs

Timing v.1.8

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate timing for other standards.
2. Measured using standard switching circuit, global routing loading of 1, worst case PTSA loading and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using GRP feedback.
5. CAM, FIFO, RAM f_{MAX} specification used shared PT Clk.

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
$t_{FIFOWES}$	Write-Enable setup before Write Clock	—	2.33	—	2.33	—	2.91	—	2.91	—	3.03	—	ns
$t_{FIFOWEH}$	Write-Enable hold after Write Clock	—	-2.95	—	-2.95	—	-2.36	—	-2.36	—	-2.27	—	ns
$t_{FIFORES}$	Read-Enable setup before Read Clock	—	2.69	—	2.35	—	2.79	—	2.38	—	4.14	—	ns
$t_{FIFOREH}$	Read-Enable hold after Read Clock	—	-3.17	—	-3.17	—	-2.53	—	-2.53	—	-2.44	—	ns
$t_{FIFORSTO}$	Reset to Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
$t_{FIFORSTR}$	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
$t_{FIFORSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
$t_{FIFORCLKO}$	Read Clock to FIFO Out Delay	—	—	3.73	—	3.73	—	4.66	—	4.66	—	4.84	ns
CAM – Update Mode													
t_{CAMMSS}	Memory Select Setup before CLK	—	1.40	—	0.70	—	1.50	—	1.40	—	1.44	—	ns
t_{CAMMSH}	Memory Select Hold after CLK	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMENMSKS}$	Enable Mask Register Setup Time before CLK	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMENMSKH}$	Enable Mask Register Setup Time after CLK	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMADDS}$	Address Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMADDH}$	Address Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMDATAS}$	Data Setup Time before Clock	—	-0.41	—	-0.41	—	-0.33	—	-0.33	—	-0.31	—	ns
$t_{CAMDATAH}$	Data Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{CAMDCS}	"Don't Care" Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t_{CAMDCH}	"Don't Care" Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{CAMRWS}	R/W Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t_{CAMRWH}	R/W Enable Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{CAMCES}	Clock Enable Setup Time before Clock	—	1.55	—	1.55	—	1.94	—	1.94	—	2.02	—	ns
t_{CAMCEH}	Clock Enable Hold Time after Clock	—	-2.95	—	-2.95	—	-2.36	—	-2.36	—	-2.27	—	ns

ispXPLD 5000MX Family Timing Adders (Continued)

Parameter	Description	Base Param.	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
HSTL_I_out	Using HSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_III_out	Using HSTL 2.5V, Class III	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
HSTL_IV_out	Using HSTL 2.5V, Class IV	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVDS_out	Using Low Voltage Differential Signaling (LVDS)	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.8	—	0.8	—	0.8	—	0.8	—	0.8	ns
LVPECL_out	Using Low Voltage PECL	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
PCI_out	Using PCI Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
SSTL2_I_out	Using SSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
SSTL2_II_out	Using SSTL 2.5V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_out	Using SSTL 3.3V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.2	—	0.2	—	0.2	—	0.2	—	0.2	ns
SSTL3_II_out	Using SSTL 3.3V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns

Timing v.1.8

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Units
t_{PWH}	Input clock, high time	80% to 80%	1.2	—	ns
t_{PWL}	Input clock, low time	20% to 20%	1.2	—	ns
t_R, t_F	Input Clock, rise and fall time	20% to 80%	—	3.0	ns
t_{INSTB}	Input clock stability, cycle to cycle (peak)		—	+/- 250	ps
f_{MDIVIN}	M Divider input, frequency range		10	320	MHz
$f_{MDIVOUT}$	M Divider output, frequency range		10	320	MHz
f_{NDIVIN}	N Divider input, frequency range		10	320	MHz
$f_{NDIVOUT}$	N Divider output, frequency range		10	320	MHz
f_{VDIVIN}	V Divider input, frequency range		100	400	MHz
$f_{VDIVOUT}$	V Divider output, frequency range		10	320	MHz
$t_{OUTDUTY}$	Output clock, duty cycle		40	60	%
$t_{JIT(CC)}$	Output clock, cycle to cycle jitter (peak)	Clean reference. 10 MHz < $f_{MDIVOUT}$ < 20 MHz or 100MHz < f_{VDIVIN} < 160 MHz[1]	—	+/- 250	ps
		Clean reference. 20 MHz < $f_{MDIVOUT}$ < 320 MHz and 160MHz < f_{VDIVIN} < 320 MHz[1]	—	+/- 150	ps
$T_{JIT(PERIOD)}$[2]	Output clock, period jitter (peak)	Clean reference. 10 MHz < $f_{MDIVOUT}$ < 20 MHz or 100MHz < f_{VDIVIN} < 160 MHz[1]	—	+/- 300	ps
		Clean reference. 20 MHz < $f_{MDIVOUT}$ < 320 MHz and 160MHz < f_{VDIVIN} < 320 MHz[1]	—	+/- 150	ps
$t_{CLK\_OUT\_DLY}$	Input clock to CLK_OUT delay	Internal feedback	—	3.0	ns
t_{PHASE}	Input clock to external feedback delta	External feedback	—	600	ps
t_{LOCK}	Time to acquire phase lock after input stable		—	25	us
t_{PLL_DELAY}	Delay increment (Lead/Lag)	Typical = +/- 250ps	+/- 120	+/- 550	ps
t_{RANGE}	Total output delay range (lead/lag)		+/- 0.84	+/- 3.85	ns
t_{PLL_RSTW}	Minimum reset pulse width		—	1.8	ns
t_{CLK_IN}[3]	Global clock input delay		—	1.0	ns
$t_{PLL\_SEC\_DELAY}$	Secondary PLL output delay (t_{PLL_DELAY})		—	1.5	ns

1. This condition assures that the output phase jitter will remain within specification.
2. Accumulated jitter measured over 10,000 waveform samples.
3. Internal timing for reference only.

Power Estimation Equations

ICC = ICC_DC + IMFB_CPLD + IMFB_ SRAM/PDPRAM/FIFO + IMFB_DPRAM + IMFB_CAM + IPLL_D

ICC_DC
Use the appropriate value for 5000MC (1.8V power supply) or 5000MV/B (2.5V/3.3V power supply) from the data sheet.

IMFB_CPLD
= ((**K0** * CPLD MFB inputs + **K1** * CPLD Logical Product Terms + **K2** * CPLD GRP from MFB + **K3** * CPLD GRP from IFB) * AF+ **K4**) * FREQ / 1000µA/mA

IMFB_CAM
= CAM Memory MFBs * ((FREQ * **K8**) + **K9**) (CAM operating in typical mode)

IMFB_ SRAM/PDPRAM/FIFO
= (WR_ PERCENT * (**K1** + WR_ PERCENT * 8 * **K0** + **K10** + **K11**) + RD_ PERCENT * (**K1** + 128 * RD_PERCENT * **K0** + 8 * OSW_PERCENT * **K2**)) * SRAM/PDPRAM/FIFO Memory MFBs * FREQ / 1000µA/mA

IMFB_ DPRAM
= (WR_ PERCENT * (2 * **K1** + 2 * WR_ PERCENT * 8 * **K0** + **K10** + **K11**) + RD_ PERCENT * (2 * **K1** + 2 * 128 * RD_PERCENT * **K0** + 8 * OSW_PERCENT * **K2**)) * DPRAM Memory MFBs * FREQ / 1000µA/mA

IPLL_D
= **K5** * PLL_FREQ * number of PLLs used. IPPL_D is the PLL digital component of the VCC supply current.

Analog portion of PLL supply current consumption, from PLL power pin:

IPLL_A = (**K6** * PLL_FREQ + **K7**) * number of PLLs used

Notes:

- ICC = Current consumption of VCC power supply (mA)
- ICC-DC = ICC DC component – Current consumption at 0Mhz (mA)
- IMFB_CPLD = CPLD (non-memory logic) current consumption (mA)
- IMFB_SRAM/PDPRAM/FIFO = Current consumption for SRAM, PDPRAM, and FIFO (mA)
- IMFB_DPRAM = Current consumption for DPRAM (mA)
- IMFB_CAM = Current consumption for CAM (mA)
- IPLL_D = PLL Current consumption of digital VCC power supply (mA)
- IPLL_A = PLL analog power pin current consumption (VCCP pin)

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
—	GCLK0N	GCLK1	—	—	—	28	J2	P7
—	—	GND	—	—	—	29	GND	GND
—	—	TDI	—	—	—	30	H6	R1
—	—	TMS	—	—	—	31	H4	R2
—	—	TCK	—	—	—	32	J6	T1
—	—	TDO	—	—	—	33	K2	V1
1	0P	A0/DATA0	B0	D0	A1	34	K3	W1
1	0N	A2/DATA1	B1	D1	A3	35	J3	Y1
1	1P	A4/DATA2	B2	D2	A5	36	J5	P3
1	1N	A6/DATA3	B3	D3	A7	37	J4	R3
1	2P	A8/DATA4	B4	D4	A9	38	L2	T2
1	2N	A10/DATA5	B5	D5	A11	39	M1	U2
—	—	GND (Bank 1)	—	—	—	40	GND (Bank 1)	GND (Bank 1)
1	3P	A12/DATA6	B6	D6	A13	41	K4	V2
—	—	V_{CCO1}	—	—	—	42	V_{CCO1}	V_{CCO1}
1	3N	A14/DATA7	B7	D7	A15	43	L3	W2
—	—	GND	—	—	—	44	GND	GND
1	4P	A16/INITB	B8	D8	A17	45	K5	R4
1	4N	A18/CSB	B9	D9	A19	46	L5	T4
1	5P	A20/READ	B10	D10	A21	47	N1	R6
1	5N	A22/CCLK	B11	D11	A23	48	M2	R5
1	6P	A24	—	—	A25	—	—	U3
—	—	VCC	—	—	—	49	VCC	VCC
1	6N	A26	—	—	A27	—	P1[1]	V3
1	7P	A28	—	—	A29	—	M3	Y2
1	7N	A30	—	—	A31	—	L4	W3
1	8P	B0	A0	—	B1	—	N2	U5
1	8N	B2	A2	—	B3	—	P2	T5
—	—	GND (Bank 1)	—	—	—	—	GND (Bank 1)	GND (Bank 1)
1	9P	B4	A4	—	—	—	R1	U4
—	—	V_{CCO1}	—	—	—	—	V_{CCO1}	V_{CCO1}
1	9N	B5	A6	—	—	—	R2	V4
1	10P	B6	A8	—	B7	—	T2	AA3
1	10N	B8	A10	—	B9	—	T3	AB3
1	—	B10	A12	—	B11	—	—	Y4
—	—	DONE	—	—	—	50	M4	AA4
1	11P	B14	B12	D12	B15	51	N3	AB4
1	11N	B16	B13	D13	B17	52	P4	AB5
1	12P	B18	B14	D14	B19	53	N5	T6
1	12N	B20	B15	D15	B21	54	M6	U7
—	—	PROGRAMB	—	—	—	55	R3	W5
1	—	B22	A14	—	B23	—	P5	U8
—	—	GND (Bank 1)	—	—	—	56	GND (Bank 1)	GND (Bank 1)

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
2	47N	G26	—	—	G27	108	N14	V19
—	—	GND (Bank 2)	—	—	—	109	GND (Bank 2)	GND (Bank 2)
2	48P	G28	F16	H16	G29	110	N16	T18
2	48N	G30	F17	H17	G31	111	M16	R17
2	49P	H0	F18	H18	H1	112	M14	U19
2	49N	H2	F19	H19	H3	113	M15	T19
2	50P	H4	E24	—	H5	—	—	V20
—	—	V_{CC}	—	—	—	114	VCC	VCC
2	50N	H6	E26	—	H7	—	NC	U20
2	51P	H8	F20	H20	H9	115	L13	W20
2	51N	H10	F21	H21	H11	116	L12	Y21
2	52P	H12	F22	H22	H13	117	L15	R18
2	52N	H14	F23	H23	H15	118	L16	R19
—	—	GND	—	—	—	119	GND	GND
2	53P	H16	F24	H24	H17	120	L14	W21
—	—	V_{CCO2}	—	—	—	121	V_{CCO2}	V_{CCO2}
2	53N	H18	F25	H25	H19	122	K15	Y22
—	—	GND (Bank 2)	—	—	—	123	GND (Bank 2)	GND (Bank 2)
2	54P	H20	F26	H26	H21	124	K14	R20
2	54N	H22	F27	H27	H23	125	K12	P20
2	55P	H24	F28	H28	H25	126	K13	T21
2	55N	H26	F29	H29	H27	127	J13	R21
2	56P	H28	F30	H30	H29	128	J14	U21
2	56N	H30	F31	H31	H31	129	J12	V21
—	—	TOE	—	—	—	130	J15	W22
—	—	RESET	—	—	—	131	J11	V22
—	—	GOE0	—	—	—	132	H11	T22
—	—	GOE1	—	—	—	133	H13	R22
—	—	GNDP	—	—	—	See Power Supply and NC Connections Table		
—	GCLK3N	GCLK2	—	—	—	135	H15	P16
—	—	V_{CCP}	—	—	—	See Power Supply and NC Connections Table		
—	GCLK3P	GCLK3	—	—	—	137	H16	N16
3	57N	I30	—	—	I31	138	H14	J22
3	57P	I28	—	—	I29	139	G16	H22
3	58N	I26	—	—	I27	140	G15	E22
3	58P	I24/PLL_FBK1	—	—	I25	141	F15	E21
3	59N	I22/PLL_RST1	I27	K27	I23	142	H12	G22
3	59P	I20	I26	K26	I21	143	G14	F21
—	—	GND (Bank 3)	—	—	—	144	GND (Bank 3)	GND (Bank 3)
3	60N	I18	I25	K25	I19	145	F16	H21
—	—	VCCO3	—	—	—	146	V_{CCO3}	V_{CCO3}
3	60P	I16	I24	K24	I17	147	E16	G21
—	—	GND	—	—	—	148	GND	GND

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
3	61N	I14	I23	K23	I15	149	G13	D22
3	61P	I12	I22	K22	I13	150	G12	D21
3	62N	I10	I21	K21	I11	151	F14	J20
3	62P	I8/CLK_OUT1	I20	K20	I9	152	E15	J19
3	63N	I6	K31	—	I7	—	F12	E20
—	—	V_{CC}	—	—	—	153	VCC	VCC
3	63P	I4	K30	L30	I5	—	F13	F20
3	64N	I2	K29	L28	I3	—	D16	H17
3	64P	I0	K28	L26	I1	—	D15	H18
—	—	GND (Bank 3)	—	—	—	—	GND (Bank 3)	GND (Bank 3)
3	65N	J30	K27	—	J31	—	—	J18
—	—	V_{CCO3}	—	—	—	—	V_{CCO3}	V_{CCO3}
3	65P	J28	K26	—	J29	—	—	H19
3	66N	J26	K25	—	J27	—	—	G20
3	66P	J24	K24	—	J25	—	—	G19
3	67N	J22	K23	—	J23	—	—	C22
3	67P	J20	K22	—	J21	—	—	C21
3	68N	J18	K21	—	J19	—	—	D20
3	68P	J16	K20	—	J17	—	—	C19
3	69N	J14	K19	—	J15	—	C16	F19
3	69P	J12	K18	—	J13	—	B16	E19
—	—	GND (Bank 3)	—	—	—	—	GND (Bank 3)	GND (Bank 3)
3	70N	J10	K17	—	J11	—	C15	G18
—	—	V_{CCO3}	—	—	—	—	V_{CCO3}	V_{CCO3}
3	70P	J8	K16	—	J9	—	B15	F18
3	71N	J6	K15	—	J7	—	E14	B20
3	71P	J4	K14	—	J5	—	D14	B19
3	72N	J2	K13	—	J3	—	E13	A20
3	72P	J0	K12	—	J1	—	A15	A19
3	73N	K30	I19	K19	K31	154	D12	D18
3	73P	K28	I18	K18	K29	155	B14	C18
3	74N	K26	I17	K17	K27	156	C13	G17
3	74P	K24	I16	K16	K25	157	A14	F16
3	75N	K22	I31	K31	K23	158	A13	E17
3	75P	K21	I30	K30	—	159	B13	D17
—	—	GND (Bank 3)	—	—	—	160	GND (Bank 3)	GND (Bank 3)
3	76N	K20	K11	L21	—	—	D11	B18
—	—	V_{CCO3}	—	—	—	161	V_{CCO3}	V_{CCO3}
3	76P	K18	K10	L20	K19	—	B12	A18
3	77N	K16	K9	L18	K17	—	C12	C17
3	77P	K14	K8	L16	K15	—	E11	B17
3	78N	K12	K7	L12	K13	—	—	C16
3	78P	K10	K6	L10	K11	—	—	B16

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
1	-	C28	D14	-	C29	P5	U8
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	15P	C26	D16	-	C27	T4	V6
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	15N	C24	D18	-	C25	T5	V7
-	-	GND	-	-	-	GND	GND
1	16P	C22	D20	-	C23	R4	Y5
-	-	VCC	-	-	-	VCC	VCC
1	16N	C20	D22	-	C21	N6	AA5
1	17P	C18	-	-	C19	R5	Y6
1	17N	C16	-	-	C17	P6	Y7
1	18P	C14	-	-	C15	—	AA6
1	18N	C12	-	-	C13	—	AA7
1	19P	C10	-	-	C11	—	W7
1	19N	C8	-	-	C9	M7	V8
1	20P	C6	-	-	C7	T6	W8
1	20N	C4	-	-	C5	R6	U9
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
-	-	CFG0	-	-	-	L8	U10
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	21P	C0	C16	A16	C1	T7	AB7
1	21N	D30	C17	A17	D31	R7	AA8
1	22P	D28	C18	A18	D29	N7	AB8
1	22N	D26	C19	A19	D27	P7	AB9
1	23P	D24	C20	A20	D25	T8	W9
1	23N	D22	C21	A21	D23	R8	Y9
1	24P	D20	C22	A22	D21	M8	AB10
1	24N	D18	C23	A23	D19	P8	AA10
1	-	D16/VREF1	-	-	D17	L9	W10
1	25P	D14	C24	A24	D15	N8	Y10
1	25N	D12	C25	A25	D13	M9	Y11
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	26P	D10	C26	A26	D11	N10	V9
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	26N	D8	C27	A27	D9	T9	V10
1	27P	D6	C28	A28	D7	T10	AA11
-	-	GND	-	-	-	GND	GND
1	27N	D4	C29	A29	D5	R9	AB11
-	-	VCC	-	-	-	VCC	VCC
1	28P	D2	C30	A30	D3	P9	U11
1	28N	D0	C31	A31	D1	N9	V11
2	29P	E0	F0	H0	E1	T11	AB12
-	-	VCC	-	-	-	VCC	VCC

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
2	46N	G6	H19	-	G7	—	AB19
2	47P	G8	H20	-	G9	—	AA19
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	47N	G10	H21	-	G11	—	U17
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	48P	G12	H22	-	G13	—	V18
2	48N	G14	H23	-	G15	—	AB21
2	49P	G16	H24	-	G17	—	U18
2	49N	G18	H25	-	G19	—	T17
2	50P	G20	H26	-	G21	R16	AB20
2	50N	G22	H27	-	G23	P16	AA20
2	51P	G24	H28	-	G25	N15	Y19
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	51N	G26	H29	-	G27	N14	V19
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	52P	G28	F16	H16	G29	N16	T18
2	52N	G30	F17	H17	G31	M16	R17
2	53P	H0	F18	H18	H1	M14	U19
2	53N	H2	F19	H19	H3	M15	T19
2	54P	H4	H30	E24	H5	—	V20
-	-	VCC	-	-	-	VCC	VCC
2	54N	H6	H31	E26	H7	—	U20
2	55P	H8	F20	H20	H9	L13	W20
2	55N	H10	F21	H21	H11	L12	Y21
2	56P	H12	F22	H22	H13	L15	R18
2	56N	H14	F23	H23	H15	L16	R19
-	-	GND	-	-	-	GND	GND
2	57P	H16	F24	H24	H17	L14	W21
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	57N	H18	F25	H25	H19	K15	Y22
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	58P	H20	F26	H26	H21	K14	R20
2	58N	H22	F27	H27	H23	K12	P20
2	59P	H24	F28	H28	H25	K13	T21
2	59N	H26	F29	H29	H27	J13	R21
2	60P	H28	F30	H30	H29	J14	U21
2	60N	H30	F31	H31	H31	J12	V21
-	-	TOE	-	-	-	J15	W22
-	-	RESET	-	-	-	J11	V22
-	-	GOE0	-	-	-	H11	T22
-	-	GOE1	-	-	-	H13	R22
-	-	GNDP	-	-	-	See Power Supply and NC Connections Table	

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
3	93N	O0	P31	N31	O1	A13	E17
3	93P	O2	P30	N30	O3	B13	D17
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	94N	O4	N11	M21	O5	D11	B18
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	94P	O6	N10	M20	O7	B12	A18
-	-	GND	-	-	-	GND	GND
3	95N	O8	N9	M18	O9	C12	C17
-	-	VCC	-	-	-	VCC	VCC
3	95P	O10	N8	M16	O11	E11	B17
3	96N	O12	N7	M12	O13	—	C16
3	96P	O14	N6	M10	O15	—	B16
3	97N	O16	N5	M8	O17	—	F13
3	97P	O18	N4	M6	O19	—	F15
3	98N	O20	N3	M5	O21	—	D16
3	98P	O22	N2	M4	O23	E10	E16
3	99N	O24	N1	M2	O25	A12	A16
3	99P	O26	N0	M0	O27	A11	A15
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	100N	O28	P15	N15	O29	B11	B15
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	100P	O30	P14	N14	O31	C11	A14
3	101N	P0	P13	N13	P1	B10	D15
3	101P	P2	P12	N12	P3	A10	E15
3	102N	P4	P11	N11	P5	C10	D14
3	102P	P6	P10	N10	P7	D10	F14
3	103N	P8	P9	N9	P9	C9	A13
3	103P	P10	P8	N8	P11	E9	B13
3	104N	P12/VREF3	P29	N29	P13	D9	C14
3	104P	P14	P28	N28	P15	F9	E14
3	105N	P16	P7	N7	P17	A9	E13
3	105P	P18	P6	N6	P19	F8	F12
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	106N	P20	P5	N5	P21	E8	D13
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	106P	P22	P4	N4	P23	A8	C13
3	107N	P24	P3	N3	P25	B9	E12
-	-	GND	-	-	-	GND	GND
3	107P	P26	P2	N2	P27	D8	C12
-	-	VCC	-	-	-	VCC	VCC
3	108N	P28	P1	N1	P29	B8	B12
3	108P	P30	P0	N0	P31	C8	A12
0	109N	Q30	Q31	S31	Q31	B7	E11

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	TCK	-	-	-	T1	P3
-	-	TDO	-	-	-	V1	P2
1	0P	A30	A0	C0	A31	—	P1
1	0N	A28	A1	C1	A29	—	R1
1	1P	A26	A2	C2	A27	—	P6
1	1N	A24	A3	C3	A25	—	R6
1	2P	A22	A4	C4	A23	—	P7
1	2N	A20	A5	C5	A21	—	R7
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	3P	A18	A6	C6	A19	—	R4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	3N	A16	A7	C7	A17	—	R5
-	-	GND	-	-	-	GND	GND
1	4P	A14	A8	C8	A15	—	R3
-	-	VCC	-	-	-	VCC	VCC
1	4N	A12	A9	C9	A13	—	R2
1	5P	A10	A10	C10	A11	—	T2
1	5N	A8	A11	C11	A9	—	T3
1	6P	A6	A12	C12	A7	—	T4
1	6N	A4	A13	C13	A5	—	T5
1	7P	A2	A14	C14	A3	—	U2
1	7N	A0	A15	C15	A1	—	U3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	8P	C30	A16	C16	C31	—	U4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	8N	C28	A17	C17	C29	—	U5
1	9P	C26	A18	C18	C27	—	T6
1	9N	C24	A19	C19	C25	—	U6
1	10P	C22	A20	C20	C23	—	T7
1	10N	C20	A21	C21	C21	—	U7
1	11P	C18	A22	C22	C19	—	U1
1	11N	C16	A23	C23	C17	—	V1
1	12P	C14	A24	C24	C15	—	V2
1	12N	C12	A25	C25	C13	—	V3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	13P	C10	A26	C26	C11	—	V5
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	13N	C8	A27	C27	C9	—	V4
-	-	GND	-	-	-	GND	GND
1	14P	C6	A28	C28	C7	—	W2
-	-	VCC	-	-	-	VCC	VCC
1	14N	C4	A29	C29	C5	—	W3
1	15P	C2	A30	C30	C3	—	W4

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
2	63P	K8	L20	-	K9	AA19	AA18
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	63N	K10	L21	-	K11	U17	Y18
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	64P	K12	L22	-	K13	V18	AD25
2	64N	K14	L23	-	K15	AB21	AD26
2	65P	K16	L24	-	K17	U18	AC23
2	65N	K18	L25	-	K19	T17	AC24
2	66P	K20	L26	-	K21	AB20	AC25
2	66N	K22	L27	-	K23	AA20	AC26
2	67P	K24	L28	-	K25	Y19	AB22
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	67N	K26	L29	-	K27	V19	AB23
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	68P	K28	J16	L16	K29	T18	AB24
2	68N	K30	J17	L17	K31	R17	AB25
2	69P	L0	J18	L18	L1	U19	AB26
2	69N	L2	J19	L19	L3	T19	AA26
2	70P	L4	L30	I24	L5	V20	AA22
-	-	VCC	-	-	-	VCC	VCC
2	70N	L6	L31	I26	L7	U20	Y21
2	71P	L8	J20	L20	L9	W20	AA23
2	71N	L10	J21	L21	L11	Y21	AA24
2	72P	L12	J22	L22	L13	R18	AA25
2	72N	L14	J23	L23	L15	R19	Y26
-	-	GND	-	-	-	GND	GND
2	73P	L16	J24	L24	L17	W21	Y22
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	73N	L18	J25	L25	L19	Y22	Y23
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	74P	L20	J26	L26	L21	R20	W20
2	74N	L22	J27	L27	L23	P20	V20
2	75P	L24	J28	L28	L25	T21	W21
2	75N	L26	J29	L29	L27	R21	V21
2	76P	L28	J30	L30	L29	U21	Y24
2	76N	L30	J31	L31	L31	V21	Y25
2	77P	N0	P0	N0	N1	—	W22
2	77N	N2	P1	N1	N3	—	W23
2	78P	N4	P2	N2	N5	—	W24
-	-	VCC	-	-	-	VCC	VCC
2	78N	N6	P3	N3	N7	—	W25
-	-	GND	-	-	-	GND	GND
2	79P	N8	P4	N4	N9	—	W26

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	79N	N10	P5	N5	N11	—	V26
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	80P	N12	P6	N6	N13	—	V22
2	80N	N14	P7	N7	N15	—	V23
2	81P	N16	P8	N8	N17	—	V24
2	81N	N18	P9	N9	N19	—	V25
2	82P	N20	P10	N10	N21	—	U20
2	82N	N22	P11	N11	N23	—	T20
2	83P	N24	P12	N12	N25	—	U26
2	83N	N26	P13	N13	N27	—	U25
2	84P	N28	P14	N14	N29	—	U21
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	84N	N30	P15	N15	N31	—	T21
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	85P	P0	P16	N16	P1	—	U22
2	85N	P2	P17	N17	P3	—	U23
2	86P	P4	P18	N18	P5	—	U24
2	86N	P6	P19	N19	P7	—	T24
2	87P	P8	P20	N20	P9	—	T23
2	87N	P10	P21	N21	P11	—	T22
2	88P	P12	P22	N22	P13	—	T25
-	-	VCC	-	-	-	VCC	VCC
2	88N	P14	P23	N23	P15	—	R26
-	-	GND	-	-	-	GND	GND
2	89P	P16	P24	N24	P17	—	R25
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	89N	P18	P25	N25	P19	—	R24
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	90P	P20	P26	N26	P21	—	R21
2	90N	P22	P27	N27	P23	—	P21
2	91P	P24	P28	N28	P25	—	R22
2	91N	P26	P29	N29	P27	—	R23
2	92P	P28	P30	N30	P29	—	R20
2	92N	P30	P31	N31	P31	—	P20
-	-	TOE	-	-	-	W22	P25
-	-	RESET	-	-	-	V22	P24
-	-	GOE0	-	-	-	T22	P23
-	-	GOE1	-	-	-	R22	P22
-	-	GNDP	-	-	-	See Power Supply and NC Connections Table	
-	GCLK3N	GCLK2	-	-	-	P16	N26
-	-	VCCP	-	-	-	See Power Supply and NC Connections Table	

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
3	126N	W4	V11	U21	W5	B18	E19
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	126P	W6	V10	U20	W7	A18	E18
-	-	GND	-	-	-	GND	GND
3	127N	W8	V9	U18	W9	C17	C24
-	-	VCC	-	-	-	VCC	VCC
3	127P	W10	V8	U16	W11	B17	C23
3	128N	W12	V7	U12	W13	C16	D22
3	128P	W14	V6	U10	W15	B16	D21
3	129N	W16	V5	U8	W17	F13	E21
3	129P	W18	V4	U6	W19	F15	D20
3	130N	W20	V3	U5	W21	D16	D19
3	130P	W22	V2	U4	W23	E16	D18
3	131N	W24	V1	U2	W25	A16	C22
3	131P	W26	V0	U0	W27	A15	C21
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	132N	W28	X15	V15	W29	B15	C20
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	132P	W30	X14	V14	W31	A14	C19
3	133N	X0	X13	V13	X1	D15	C18
3	133P	X2	X12	V12	X3	E15	C17
3	134N	X4	X11	V11	X5	D14	B24
3	134P	X6	X10	V10	X7	F14	B23
3	135N	X8	X9	V9	X9	A13	B22
3	135P	X10	X8	V8	X11	B13	B21
3	136N	X12/VREF3	X29	V29	X13	C14	B20
3	136P	X14	X28	V28	X15	E14	B19
3	137N	X16	X7	V7	X17	E13	B18
3	137P	X18	X6	V6	X19	F12	B17
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	138N	X20	X5	V5	X21	D13	A24
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	138P	X22	X4	V4	X23	C13	A23
3	139N	X24	X3	V3	X25	E12	A22
-	-	GND	-	-	-	GND	GND
3	139P	X26	X2	V2	X27	C12	A21
-	-	VCC	-	-	-	VCC	VCC
3	140N	X28	X1	V1	X29	B12	A20
3	140P	X30	X0	V0	X31	A12	A19
0	141N	Y30	Y31	AA31	Y31	E11	A18
-	-	VCC	-	-	-	VCC	VCC
0	141P	Y28	Y30	AA30	Y29	C11	A17
-	-	GND	-	-	-	GND	GND

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
December 2003	07	Added ispXPLD 5768MX information (supply current, timings, power consumption, power estimation coefficients, memory coefficients, logic signal connections, ordering part numbers).
		Updated ispXPLD 5000MX timing numbers (version v.1.7).
		Added lead-free package designator.
		Removed ispXPLD 5000MC industrial temperature grade ordering part numbers.
January 2004	08	Lead-free package release for the ispXPLD 5000MC and 5000MV devices.
		Timing model parameter tCOi correction - Maximum specification instead of Minimum (no changes in the timing numbers).
March 2004	08.1	Updated the MFB Cascade Chain table for the ispXPLD 5256MX device.
May 2004	09	Updated the ispXPLD 5000MX timig numbers (version v.1.8) ispXPLD 5256MC, 5512MC and 51024MC industrial temperature grade devices release
		Updated typical supply current data and condition.
		ispXPLD 5256MX 256-fpBGA logic signal connection tables: Removed internal signal description for ball H5 and G14.
August 2004	10	Added footnote "1, page 49. These inputs should not toggle during power up for proper power-up configuration." to CCLK and READ.
		Added ispXPLD 5768MC Industrial grade OPNs (Conventional and Lead-Free).
October 2004	10.1	Figure 19, LVPECL Driver with Three Resistor Pack has been updated (ispXPLD LVPECL Buffer changed to ispXPLD Emulated LVPECL Buffer)
November 2004	11	Added ispXPLD 5000MB (2.5V) Lead-Free Ordering Part Numbers.
December 2004	11.1	Pin name RESETB has been updated to RESET.
March 2005	12	208-PQFP Lead-free package release for the ispXPLD 5512MV/B/C devices.
April 2005	12.1	Page 23, clarification of footnote regarding IDK specification.
March 2006	12.2	Signal description for RESET has been updated.
April 2009	12.3	Ordering Information section has been updated to describe alternate LC5768MB/MV top side marking format.
February 2010	12.4	References to "system gates" changed to "functional gates."